

| Layer | Name                   | Material      | Thickness | Constant | Board Layer Stack |
|-------|------------------------|---------------|-----------|----------|-------------------|
| 1     | Top Overlay            |               |           |          |                   |
| 2     | Top Solder             | Solder Resist | 0.40mil   | 3.5      |                   |
| 3     | Layer 1 - Top Layer    | Copper        | 1.40mil   |          |                   |
| 4     | Dielectric 1           | 370HR         | 12.60mil  | 4.2      |                   |
| 5     | Layer 2 - GND          | Copper        | 1.40mil   |          |                   |
| 6     | Dielectric 2           | 370HR         | 8.00mil   | 4.2      |                   |
| 7     | Layer 3 - Signal       | Copper        | 1.42mil   |          |                   |
| 8     | Dielectric 3           | 370HR         | 16.60mil  | 4.2      |                   |
| 9     | Layer 4 - Signal       | Copper        | 1.42mil   |          |                   |
| 10    | Dielectric 4           | 370HR         | 8.00mil   | 4.2      |                   |
| 11    | Layer 5 - PWR          | Copper        | 1.40mil   |          |                   |
| 12    | Dielectric 5           | 370HR         | 12.60mil  | 4.2      |                   |
| 13    | Layer 6 - Bottom Layer | Copper        | 1.40mil   |          |                   |
| 14    | Bottom Solder          | Solder Resist | 0.40mil   | 3.5      |                   |
| 15    | Bottom Overlay         |               |           |          |                   |

**DESIGN INFORMATION**

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
795.28MIL X 795.28MIL

Number of Layers : 6  
 MIN. TRACK WIDTH: 5 MIL  
 MIN. CLEARANCE: 4 MIL  
 MIN. VIA PAD SIZE: 10 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
 PER IPC-D-275 CLASS 2 LEVEL C  
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

**MATERIAL:**  
 FR-408  FR-4 High Tg  OTHER \_\_\_\_\_

THICKNESS:  62 MIL (1.6mm) +/-10%  OTHER \_\_\_\_\_

TOLERANCE:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

BOW & TWIST:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

**COPPER THICKNESS (FINISHED):**  
 OUTER:  1.4MIL (1oz)  2MIL (1.4oz)  2.8MIL (2oz)  
 INNER SIGNAL:  1.4MIL (1oz)  2.8MIL (2oz)  N/A

**DRILLING:**  
 REFERENCE:  AS SHOWN  NC\_DRILL FILES  
 PTH MIN COPPER THICKNESS:  1MIL  OTHER \_\_\_\_\_

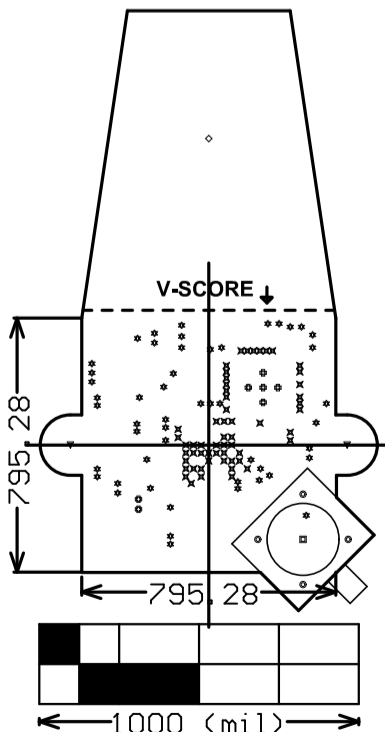
**BOARD FINISH:**  
 SILKSCREEN:  TOP  BOTTOM  
 SILKSCREEN COLOR:  WHITE  OTHER \_\_\_\_\_  
 SOLDER RESIST COLOR:  
 GREEN  BLUE  OTHER BLACK

**SURFACE FINISH:**  IMMERSION GOLD (ENIG)  ENEPIG  
 IMM. TIN/SILVER OR EQUIV  OTHER \_\_\_\_\_

**ARRAY/PANEL:**  CUT AND TRIM PER MECH LAYER 1  
 N.C. ROUTE  V. SCORE

**CERTIFICATION:** MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
 ANSI IPC-A-600F CLASS ->  1  2  3  
 UL 94V-0  RoHS  OTHER PER ORDER

**ADDITIONAL REQUIREMENTS:**  
 MICROSECTION:  YES  
 BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER  
 MANUFACTURER'S UL:  RAL  METAL  SILK



| Symbol | Quantity  | Finished Hole Size  | Plated | Hole Type | Drill Layer Pair                             | Hole Tolerance |
|--------|-----------|---------------------|--------|-----------|--|----------------|
| ▽      | 2         | 62.99mil (1.600mm)  | NPTH   | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
| ◇      | 1         | 280.00mil (7.112mm) | NPTH   | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
| ✕      | 56        | 6.00mil (0.152mm)   | PTH    | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
| ⊕      | 7         | 7.87mil (0.200mm)   | PTH    | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
| ⊗      | 50        | 10.00mil (0.254mm)  | PTH    | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
| ⊙      | 1         | 35.43mil (0.900mm)  | PTH    | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
| ⊚      | 4         | 55.12mil (1.400mm)  | PTH    | Round     | Layer 1 - Top Layer - Layer 6 - Bottom Layer |                |
|        | 121 Total |                     |        |           |  |                |

**TEXAS INSTRUMENTS**

PROJECT TITLE:  
TIDA-01130

DESIGNED FOR:  
Public Release

FILE NAME:  
TIDA-01130.PcbDoc

ENGINEER:  
Shaffer & Bianchi

LAYOUT BY:  
JMM **krypton solutions**

SCALE: 1.00

ALTIUM DESIGNER VERSION:  
17.0.11.656

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